

PACKAGE STRUCTURE

ABSTRACT OF THE DISCLOSURE

A package structure includes a first insulation layer, a first conductive layer, a direct bond copper substrate, and a first electronic component. A first conductive via is formed in the first insulation layer. The first conductive layer is disposed on a top surface of the first insulation layer and in contact with the first conductive via. The direct bond copper substrate includes a second conductive layer, a third conductive layer and a ceramic base. The ceramic base is disposed on a bottom surface of the first insulation layer and exposed to the first insulation layer by press-fit operation. The first electronic component is embedded within the first insulation layer and disposed on the second conductive layer. The first electronic component includes a first conducting terminal. The first conducting terminal is electrically connected with the second conductive layer and/or electrically connected with the first conductive layer through the first conductive via.

Fig. 1A